Title (en)

LOUD SPEAKER ARRANGEMENT WITH CIRCUIT-BOARD-INTEGRATED ASIC

Title (de)

LAUTSPRECHERANORDNUNG MIT LEITERPLATTENINTEGRIERTEM ASIC

Title (fr)

SYSTÈME DE HAUT-PARLEUR MUNI D'UN CIRCUIT ASIC INTÉGRÉ DANS UNE CARTE DE CIRCUIT IMPRIMÉ

Publication

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Application

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Abstract (en)

[origin: WO2015162248A1] The present invention relates to a loud speaker arrangement (1) with a circuit board (2), an MEMS loudspeaker (3) for producing sound waves in the audible wavelength spectrum, said MEMS loud speaker having a membrane (9) deflectable along a z-axis, a sound-conducting channel (21) adjacent to the MEMS loudspeaker (3) with an acoustic outlet opening (22) and an ASIC (4) electrically connected to the MEMS loudspeaker (3). Further, the circuit board (2) comprises a first circuit board cavity (11) in which the ASIC (4) is arranged so as to be fully integrated in the circuit board (2). Further, the circuit board (2) comprises a second circuit board cavity (13) with an opening (14), said opening being closed by means of the MEMS loudspeaker (3) so that the second circuit board cavity (13) forms at least one part of a cavity (15) of the MEMS loudspeaker (3). According to the invention, the sound-conducting channel (21) extends obliquely to the z-axis of the MEMS loudspeaker. Moreover, the acoustic outlet opening (22) is arranged on the lateral surface of the loudspeaker arrangement (1).

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